IEEE INTERCON 2022

August 11ᵀᴴ to 13ᵀᴴ, 2022 - Lima, Peru

CALL FOR PAPERS

The **2022 IEEE XXIX International Conference on Electronics, Electrical Engineering and Computing – INTERCON** aims to bring together researchers, professionals, students and entrepreneurs to facilitate the approach, identification and commitment to join challenges that allow the development of technologies for the benefit of humanity.

2022 INTERCON will be held at Universidad Nacional Mayor de San Marcos. This university is one of the main educational institutions in Peru and is located in the district of Lima, Lima.

CFP INTERCON 2022 has been redesigned in a virtual environment, for the safety of our community and to offer an inclusive experience.

For oral presentations, will use teleconferences tools to prepare interactive presentation sessions. Remote hosts will use a common remote presence software tool which will be determined and announced by the organizing committee.

The topics include, but they are not limited to:

- Communication systems
- Semiconductor and devices
- Computers and information technology
- Signal processing
- Systems and control
- Emerging technologies
- Circuits and systems
- Power generation, transmission and distribution
- Renewable energy sources, smartgrids technologies
- Optoelectronic materials, devices and systems
- Climatic change & Renewable energy
- DC systems in High Voltage, BESS and nuclear power plants

- Power electronics, systems and applications
- Electrical machines and adjustable speed drives
- High voltage engineering and insulation technology
- Algorithms and complexity
- Architecture and organization
- Graphics and visualization
- Information management, assurance and security
- Intelligent systems
- Parallel and distributed Computing
- Software engineering
- Social issues and professional practice
- Research & Development restrictions and improvements

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INTERCON 2022

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Submission

• The official language of 2022 IEEE INTERCON is ENGLISH. The maximum number of authors per paper, including co-authors is four (4). Papers must be submmited in PDF and no longer than four (4) pages, following the IEEE Conference Template available at:
https://www.ieee.org/conferences/publishing/templates.html
• We will use EasyChair system for submissions here:
https://easychair.org/conferences/?conf=2022ieeeintercon
• Accepted technical papers will be submitted to the IEEE Xplore Digital Library.

Registration

All accepted papers will need one associated registration with the Call For Papers INTERCON 2022 for being included in the technical program and conference proceedings.

Publication

As is mandatory for any IEEE conference, we will implement a strict policy of "No show", no "Publication" adapted to the virtual environment of INTERCON 2022 which means that accepted documents that are not presented by the videoconference tool will not be submitted for publication in the conference at IEEE Xplore. These presentations must be made using the virtual tools that will be defined and announced by the organizing committee, so that registered participants and authors can talk and exchange their experiences and points of view through the online tool. This discussions are a valuable quality element of our conference.

All papers submitted through EasyChair will be previously reviewed and all the accepted papers, if presented at 2022
INTERCON, will be submitted for publication in IEEE Xplore.

XXIX International Conference on Electronics, Electrical Engineering and Computing

Important Dates

Full paper submission deadline: May 15, 2022
Notification of acceptance: June 30, 2022
Final paper submission deadline: July 10, 2022
Autor registration deadline: July 15, 2022
Oral presentations: August 11 to 13, 2022

Sponsored by

• IEEE Peru Section *(www.ieee.org.pe)*
• Universidad Nacional Mayor de San Marcos
  IEEE Student Branch.

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